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PESD3V3Z1BSF

Extremely low capacitance bidirectional ESD protection diode

Product data sheet

1. General description

Extremely low capacitance bidirectional ElectroStatic Discharge (ESD) protection diode, which is part of the TrEOS protection family. The device is housed in a DSN0603-2 (SOD962-2) leadless ultra small Surface-Mounted Device (SMD) package designed to protect one signal line from damage caused by ESD and other transients.

2. Features and benefits

- Bidirectional ESD protection of one line
- Extremely low diode capacitance $C_d = 0.28 pF$
- Extremely low clamping voltage to protect sensitive I/Os
- · Extremely low inductance protection path to ground
- ESD protection up to 20 kV according to IEC 61000-4-2
- Ultra small SMD package
- 9.5 A maximum 8/20 µs peak pulse current

3. Applications

- Cellular handsets and accessories
- Portable electronics
- Communication systems
- Computers and peripherals

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V_{RWM}	reverse standoff voltage	T _{amb} = 25 °C	-	-	3.3	V
C _d	diode capacitance	f = 1 MHz; V _R = 0 V; T _{amb} = 25 °C	-	0.28	0.35	pF



5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K1	cathode		K1 F (1 D) K2
2	K2	cathode		sym045
			Transparent top view	
			DSN0603-2 (SOD962-2)	

6. Ordering information

Table 3. Ordering information

Type number	Package				
	Name	Description	Version		
PESD3V3Z1BSF	DSN0603-2	Leadless ultra small package; 2 terminals; body 0.6 x 0.3 x 0.3 mm	SOD962-2		

7. Marking

Table 4. Marking codes

Type number	Marking code
PESD3V3Z1BSF	U

8. Limiting values

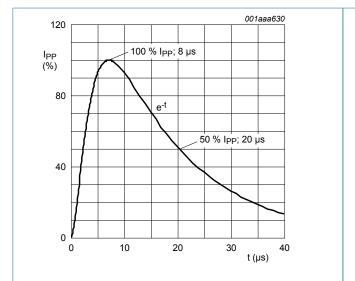
Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134)

Symbol	Parameter	Conditions		Min	Max	Unit
I _{PPM}	rated peak pulse current	t _p = 8/20 μs	[1]	-	9.5	Α
Tj	junction temperature			-	150	°C
T _{amb}	ambient temperature			-40	125	°C
T _{stg}	storage temperature			-65	150	°C
ESD maximum	ratings					
V _{ESD}	electrostatic discharge	IEC 61000-4-2; contact discharge	[2]	-20	20	kV
	voltage	IEC 61000-4-2; air discharge	<u>[2]</u>	-20	20	kV

^[1] Non-repetitive current pulse 8/20 µs exponentially decaying waveform according to IEC61000-4-5.

^[2] Device stressed with ten non-repetitive ESD pulses.





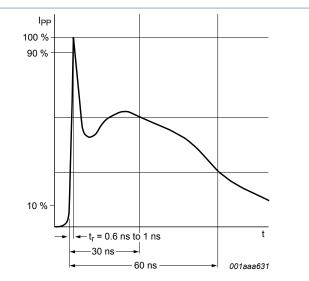


Fig. 2. ESD pulse waveform according to IEC 61000-4-2

9. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V _{RWM}	reverse standoff voltage	T _{amb} = 25 °C		-	-	3.3	V
V_{BR}	breakdown voltage	I _R = 1 mA; T _{amb} = 25 °C		-	6.9	-	V
I _{RM}	reverse leakage current	V _{RWM} = 3.3 V; T _{amb} = 25 °C		-	1	50	nA
C _d	diode capacitance	f = 1 MHz; V _R = 0 V; T _{amb} = 25 °C		-	0.28	0.35	pF
		f = 1 MHz; V _R = 1.5 V; T _{amb} = 25 °C		-	0.25	-	pF
V _{CL}	clamping voltage	I _{PP} = 4 A; T _{amb} = 25 °C	[1]	-	3.7	-	V
		I _{PPM} = 9.5 A; T _{amb} = 25 °C	[1]	-	5.3	-	V
R _{dyn}	dynamic resistance	4 A ≤ I _R ≤ 16 A; T _{amb} = 25 °C	[2]	-	0.19	-	Ω
		-4 A ≤ I _R ≤ -16 A; T _{amb} = 25 °C	[2]	-	0.19	-	Ω
f _{-3dB}	-3 dB cut-off frequency	T _{amb} = 25 °C; Normalized to attenuation at 1 MHz		-	17	-	GHz

^[1] Non-repetitive current pulse 8/20 µs exponential decay waveform according to IEC 61000-4-5.

^[2] Non-repetitive current pulse, Transmission Line Pulse (TLP) tp = 100 ns; square pulse; pulser at 70 ns to 90 ns; ANSI / ESD STM5.5.1-2008.

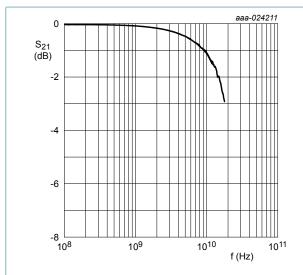


Fig. 3. Insertion loss; typical values

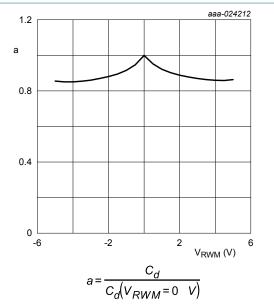


Fig. 4. Relative capacitance as a function of reverse standoff voltage; typical values

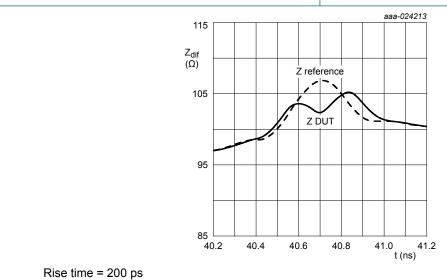
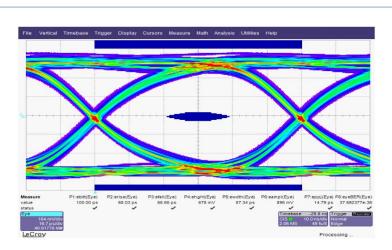


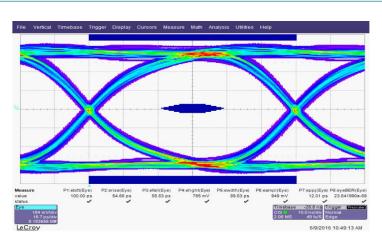
Fig. 5. Differential Time Domain Reflectometer (TDR) plot; typical values



aaa-024214

Data rate: 10 Gbit/s

Fig. 6. USB 3.2 eye diagram, PCB with device; typical values

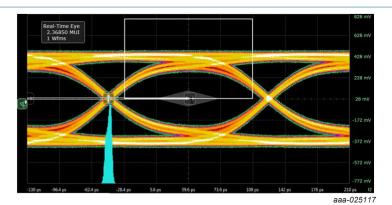


aaa-024215

Data rate: 10 Gbit/s

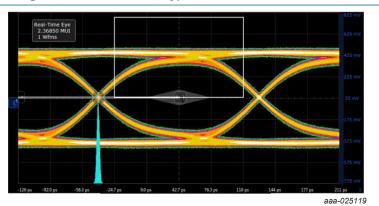
Fig. 7. USB 3.2 eye diagram, PCB without device; typical values

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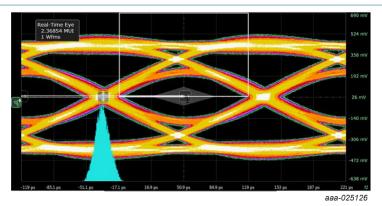
Test frequency: 148.5 MHz Differential swing voltage: 845 mV Horizontal scale: 34 ps/div Vertical scale: 200 mV/div

Fig. 8. HDMI 2.0 TP1 eye diagram, PCB with device; typical values



Test frequency: 148.5 MHz Differential swing voltage: 844 mV Horizontal scale: 34 ps/div Vertical scale: 200 mV/div

Fig. 9. HDMI 2.0 TP1 eye diagram, PCB without device; typical values

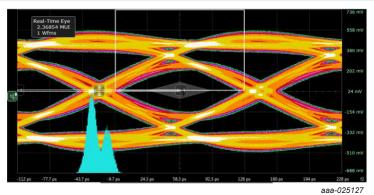


Test frequency: 148.5 MHz Differential swing voltage: 806 mV Horizontal scale: 34 ps/div Vertical scale: 266 mV/div

Remark: Measured at Test Point 2 (TP2) worst cable emulator, reference cable equalizer and worst case positive

skew

Fig. 10. HDMI 2.0 TP2 eye diagram, PCB with device; typical values



Test frequency: 148.5 MHz

Differential swing voltage: 823 mV Horizontal scale: 34 ps/div Vertical scale: 178 mV/div

Remark: Measured at Test Point 2 (TP2) worst cable emulator, reference cable equalizer and worst case positive

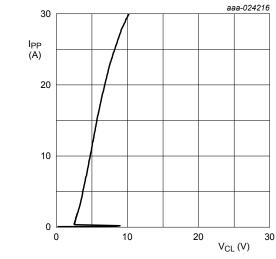
skew

Fig. 11. HDMI 2.0 TP2 eye diagram, PCB without device; typical values

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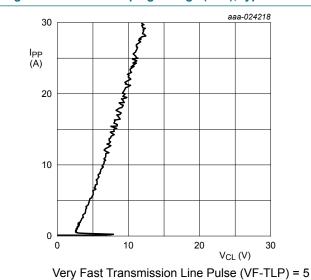
Extremely low capacitance bidirectional ESD protection diode

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Transmission Line Pulse (TLP) = 100 ns; rise time = 1 ns

Fig. 12. Positive clamping voltage (TLP); typical values

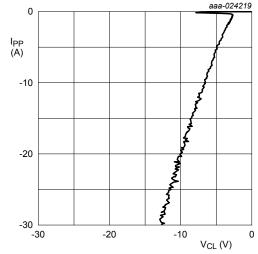


ns Fig. 14. Positive clamping voltage (VF-TLP); typical

-20
-30
-30
-20
-10
V_{CL} (V)

Transmission Line Pulse (TLP) = 100 ns; rise time = 1 ns

Fig. 13. Negative clamping voltage (TLP); typical values



Very Fast Transmission Line Pulse (VF-TLP) = 5 ns

Fig. 15. Negative clamping voltage (VF-TLP); typical values

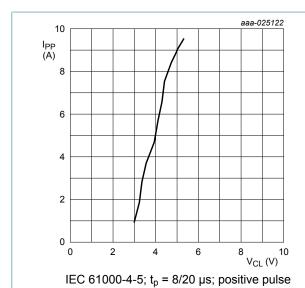


Fig. 16. Dynamic resistance with positive clamping; typical values

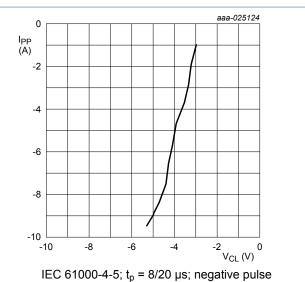
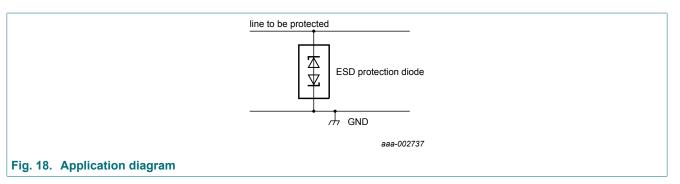


Fig. 17. Dynamic resistance with negative clamping; typical values

10. Application information

The device is designed for the protection of one bidirectional data line from surge pulses and ESD damage. The device is suitable on lines where the signal polarities are both positive and negative with respect to ground.

The device uses an advanced clamping structure showing a negative dynamic resistance. This snap-back behavior strongly reduces the clamping voltage to the system behind the ESD protection during an ESD event. Do not connect unlimited DC current sources to the data lines to avoid keeping the ESD protection device in snap-back state after exceeding breakdown voltage (due to an ESD pulse for instance).

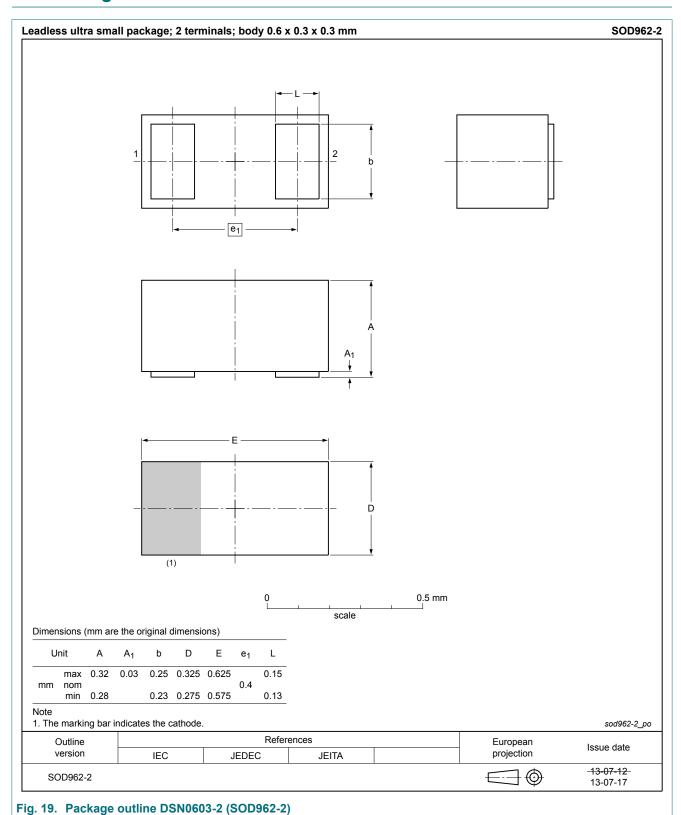


Circuit board layout and protection device placement

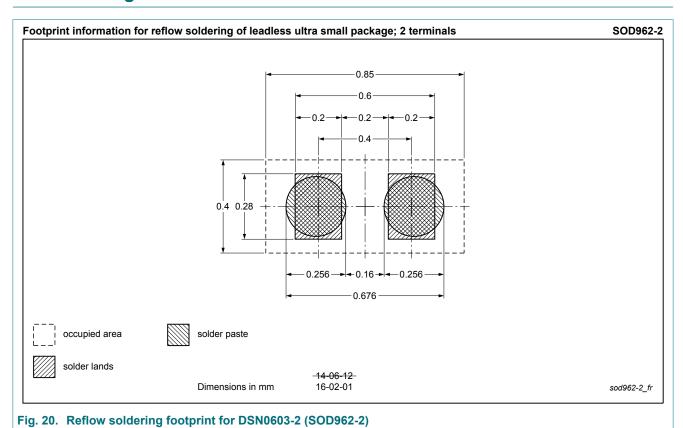
Circuit board layout is critical for the suppression of ESD, Electrical Fast Transient (EFT) and surge transients. The following guidelines are recommended:

- 1. Place the device as close to the input terminal or connector as possible.
- 2. Minimize the path length between the device and the protected line.
- 3. Keep parallel signal paths to a minimum.
- 4. Avoid running protected conductors in parallel with unprotected conductors.
- 5. Minimize all Printed-Circuit Board (PCB) conductive loops including power and ground loops.
- 6. Minimize the length of the transient return path to ground.
- 7. Avoid using shared transient return paths to a common ground point.
- 8. Use ground planes whenever possible. For multilayer PCBs, use ground vias.

11. Package outline



12. Soldering



13. Revision history

Table 7. Revision history

Tuble 7. Revision history					
Data sheet ID	Release date	Data sheet status	Change notice	Supersedes	
PESD3V3Z1BSF v.3	20180705	Product data sheet	-	PESD3V3Z1BSF v.2	
Modifications:	Nexperia.	at of this data sheet has been redesigned to comply with the identity guid s have been adapted to the new company name where appropriate. and 5 corrected		, ,	
PESD3V3Z1BSF v.2	20170116	Product data sheet	-	PESD3V3Z1BSF v.1	
PESD3V3Z1BSF v.1	20161031	Preliminary data sheet	-	-	

14. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at https://www.nexperia.com.

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